

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSZ097N04LS G	**Issued**	28. October 2019
MA#	MA001307566		
Package	PG-TSDSON-8-1	**Weight***	36.12 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.804	2.23	2.23	22256	22256
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		66	
	non noble metal	zinc	7440-66-6	0.009	0.03		262	
	non noble metal	iron	7439-89-6	0.189	0.52		5242	
	non noble metal	copper	7440-50-8	7.689	21.29	21.85	212859	218429
wire	non noble metal	copper	7440-50-8	0.038	0.11	0.11	1052	1052
encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1033	
	plastics	epoxy resin	-	1.921	5.32		53174	
	inorganic material	silicondioxide	60676-86-0	16.690	46.21	51.63	462049	516256
leadfinish	non noble metal	tin	7440-31-5	0.370	1.02	1.02	10245	10245
plating	noble metal	silver	7440-22-4	0.081	0.22	0.22	2237	2237
solder	non noble metal	tin	7440-31-5	0.022	0.06		615	
	noble metal	silver	7440-22-4	0.028	0.08		768	
	non noble metal	lead	7439-92-1	1.060	2.93	3.07	29349	30732
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001	0.00		27	
	non noble metal	zinc	7440-66-6	0.004	0.01		108	
	non noble metal	iron	7439-89-6	0.078	0.22		2169	
	non noble metal	copper	7440-50-8	3.182	8.81	9.04	88084	90388
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		33	
	non noble metal	zinc	7440-66-6	0.005	0.01		130	
	non noble metal	iron	7439-89-6	0.094	0.26		2602	
	non noble metal	copper	7440-50-8	3.816	10.56	10.83	105640	108405
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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